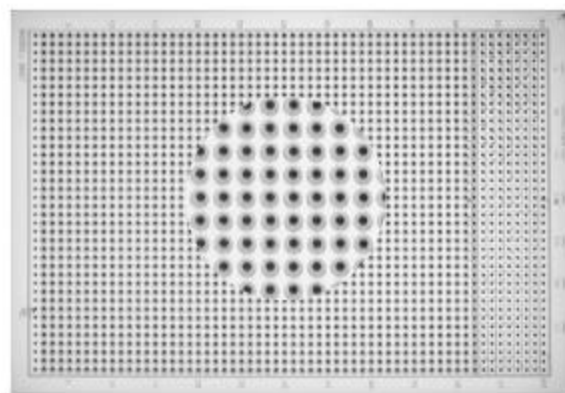
**8004**

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

4.5" x 6.5"

Ground Plane
 N/A
 6.50"/.062"
 4.50"
 50
 CEM-1
 T44, T46, T49, T68
 T42-1
 R32
 .042"

- 0.100" grid
- To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately
- 0.080" diameter clearance around each hole
- Plane surfaces solder-coated for user convenience
- I/O area with square solder pads for mounting connector
- Single sided prototyping area with overall Ground Plane only

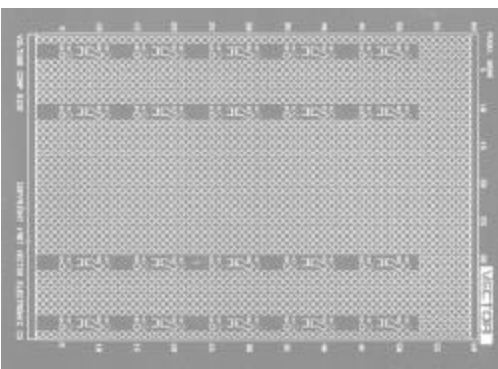
**8007**

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

4.5" x 6.5"

Pad-Per-Hole &
 Ground Plane
 N/A
 6.50"/.062"
 4.50"
 60
 CEM-1
 T44, T46, T49, T68
 T42-1
 R32
 .042"

- 0.100" grid
- Pad-Per-Hole pattern on component side - overall Ground Plane pattern on wiring side - holes not plated through
- To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately
- 0.080" diameter, isolated solder pad around holes, component side
- Accommodates any type DIP IC device or discrete
- Plane surfaces solder-coated for user convenience

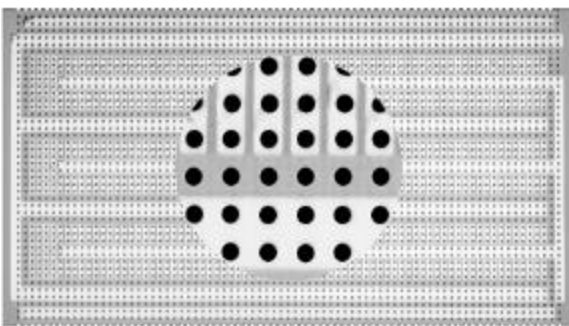
**8008**

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

4.5" x 6.5"

Pad & Planes
 2 sides
 N/A
 6.50"/.062"
 4.50"
 70
 FR4 Epoxy Glass
 T44, T46, T49, T68
 T42-1
 R32
 .042"

- 0.100" grid
- Unique circuit pattern features full voltage and ground planes on both sides with isolated, plated-thru holes
- 0.080" diameter, isolated solder pad around holes, component side
- Plane surfaces solder-coated for user convenience
- SMD cap positions for discrete decoupling capacitors

**3677-6**

Circuit Pattern:
Contacts:
Width/Thick:
Height:
16-Pin DIP Capacity:
Material:
Wire-Wrap Terminals:
Solder Terminals:
Wire-Wrap Socket Pins:
Hole Diameter:

4.5" x 8.08"

3-Hole Solder Pad
 N/A
 8.08"/.062"
 4.50"
 21
 CEM-1
 T44, T46, T49, T68
 T42-1
 R32
 .042"

- 0.100" grid
- Precision-drilled, not plated-thru holes
- Board side and surface area approximate Macintosh II specifications
- Unrestricted component placement
- Single-sided with no etch or plating on reverse side